

98-106/7/8C

Application No. 09/817,473

Gp/2813
#10/B
4-24-03
Mullish

October 17, 2002

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TO: Commissioner of Patents and Trademarks
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FROM: George O. Saile, Reg. No. 19,572
28 Davis Ave.
Poughkeepsie, N.Y. 12603


SUBJECT: Serial #: 09/817,473
File Date: 03/26/2001
Inventor: YI, XU ET AL.
Examiner: NGUYEN, THANH T.
Art Unit: 2813
Title: GAP FILLING PROCESS IN INTEGRATED
CIRCUITS USING LOW DIELECTRIC CONSTANT
MATERIALS

RESPONSE TO OFFICE ACTION

This is in response to the Office Action dated July 17,
2002. Please consider the following regarding the above
referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited
with the United States Postal Service as first class mail in an
envelope addressed to: Commissioner of Patents and Trademarks,
Washington, D.C. 20231 on October 17, 2002.

Signature  Date: Oct. 17, 2002
Stephen B. Ackerman, Reg. No. 37,761